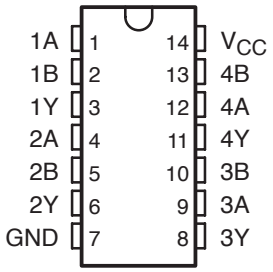
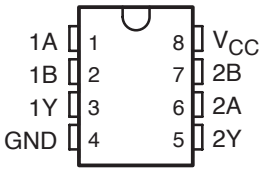
- **Package Options Include Plastic Small-Outline (D, NS, PS), Shrink Small-Outline (DB), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) DIPs**
- **Also Available as Dual 2-Input Positive-NAND Gate in Small-Outline (PS) Package**

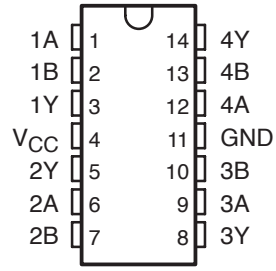
**SN5400 . . . J PACKAGE**
**SN54LS00, SN54S00 . . . J OR W PACKAGE**
**SN7400, SN74S00 . . . D, N, OR NS PACKAGE**
**SN74LS00 . . . D, DB, N, OR NS PACKAGE**
**(TOP VIEW)**



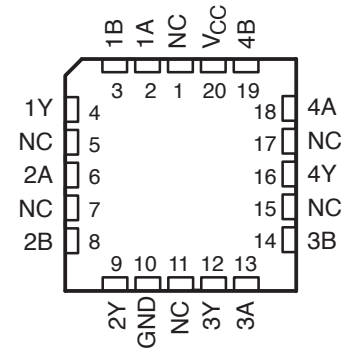

**SN74LS00, SN74S00 . . . PS PACKAGE**
**(TOP VIEW)**




**SN5400 . . . W PACKAGE**
**(TOP VIEW)**




**SN54LS00, SN54S00 . . . FK PACKAGE**
**(TOP VIEW)**




NC – No internal connection

## description/ordering information

These devices contain four independent 2-input NAND gates. The devices perform the Boolean function $Y = \overline{A \bullet B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



TEXAS INSTRUMENTS

## description/ordering information (continued)

**ORDERING INFORMATION**

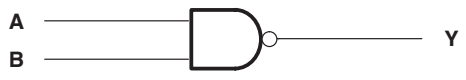
| $T_A$ | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---|---|---|---|---|
| 0°C to 70°C | PDIP – N | Tube | SN7400N | SN7400N |
| | | | SN74LS00N | SN74LS00N |
| | | | SN74S00N | SN74S00N |
| | SOIC – D | Tube | SN7400D | 7400 |
| | | Tape and reel | SN7400DR | |
| | | Tube | SN74LS00D | LS00 |
| | | Tape and reel | SN74LS00DR | |
| | | Tube | SN74S00D | S00 |
| | | Tape and reel | SN74S00DR | |
| | SOP – NS | Tape and reel | SN7400NSR | SN7400 |
| | | | SN74LS00NSR | 74LS00 |
| | | | SN74S00NSR | 74S00 |
| | SOP – PS | Tape and reel | SN74LS00PSR | LS00 |
| | | | SN74S00PSR | S00 |
| | SSOP – DB | Tape and reel | SN74LS00DBR | LS00 |
| –55°C to 125°C | CDIP – J | Tube | SNJ5400J | SNJ5400J |
| | | | SNJ54LS00J | SNJ54LS00J |
| | | | SNJ54S00J | SNJ54S00J |
| | CFP – W | Tube | SNJ5400W | SNJ5400W |
| | | | SNJ54LS00W | SNJ54LS00W |
| | | | SNJ54S00W | SNJ54S00W |
| | LCCC – FK | Tube | SNJ54LS00FK | SNJ54LS00FK |
| | | | SNJ54S00FK | SNJ54S00FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

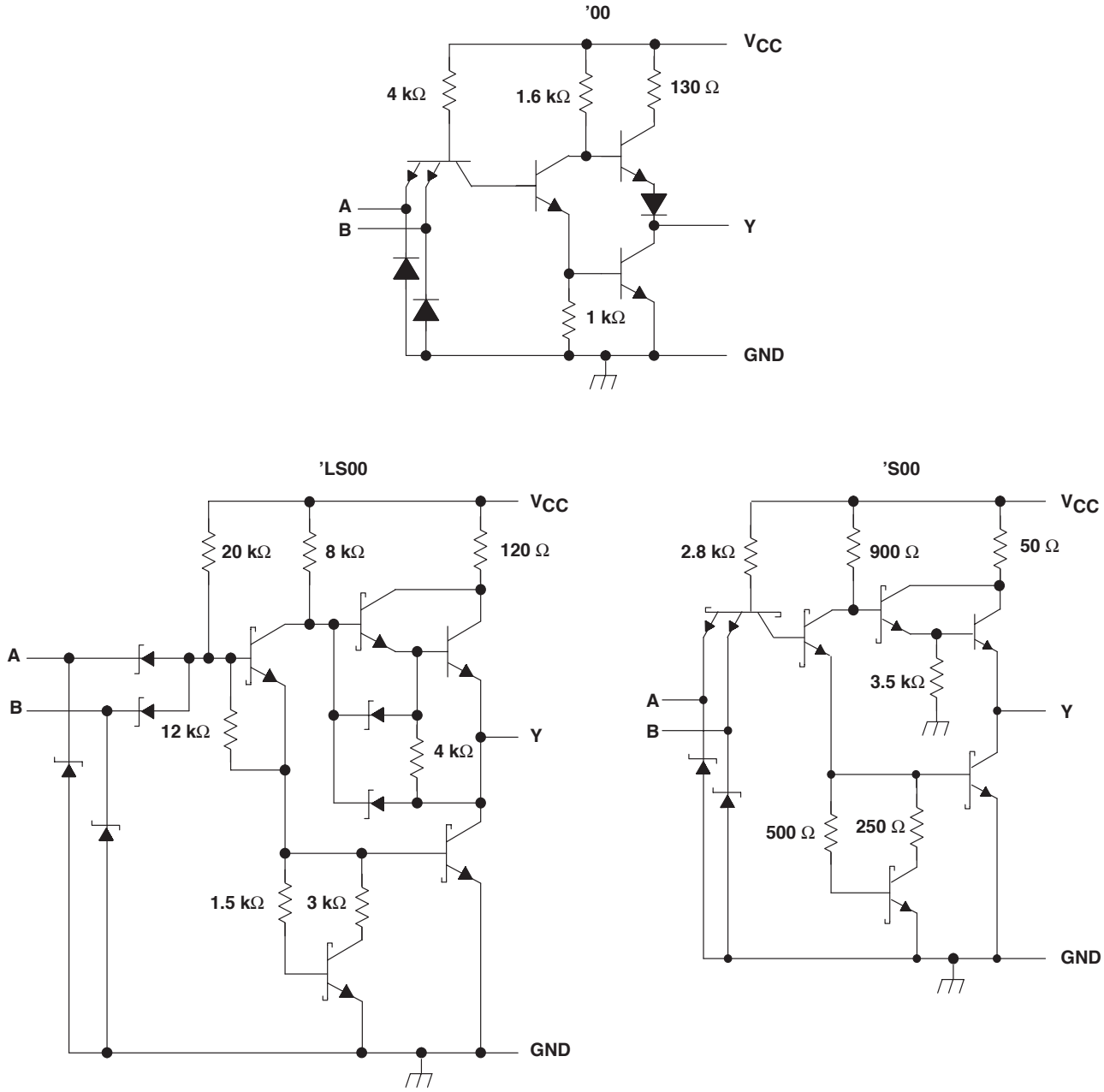
**FUNCTION TABLE**
**(each gate)**

| INPUTS | | OUTPUT |
|---|---|---|
| A | B | Y |
| H | H | L |
| L | X | H |
| X | L | H |

## logic diagram, each gate (positive logic)



## schematic




Resistor values shown are nominal.

### absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, $V_{CC}$ (see Note 1) . . . . . 7 V
Input voltage: ’00, ’S00 . . . . . 5.5 V
’LS00 . . . . . 7 V
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package . . . . . 86°C/W
DB package . . . . . 96°C/W
N package . . . . . 80°C/W
NS package . . . . . 76°C/W
PS package . . . . . 95°C/W
Storage temperature range, $T_{stg}$ . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Voltage values are with respect to network ground terminal.
2. The package termal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

| | | SN5400 | | | SN7400 | | | UNIT |
|---|---|---|---|---|---|---|---|---|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| $V_{CC}$ | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| $V_{IH}$ | High-level input voltage | 2 | | | 2 | | | V |
| $V_{IL}$ | Low-level input voltage | | | 0.8 | | | 0.8 | V |
| $I_{OH}$ | High-level output current | | | –0.4 | | | –0.4 | mA |
| $I_{OL}$ | Low-level output current | | | 16 | | | 16 | mA |
| $T_A$ | Operating free-air temperature | –55 | | 125 | 0 | | 70 | °C |

NOTE 3: All unused inputs of the device must be held at $V_{CC}$ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS‡ | | | SN5400 | | | SN7400 | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP§ | MAX | MIN | TYP§ | MAX | |
| $V_{IK}$ | $V_{CC}$ = MIN, | $I_I$ = –12 mA | | | | –1.5 | | | –1.5 | V |
| $V_{OH}$ | $V_{CC}$ = MIN, | $V_{IL}$ = 0.8 V, | $I_{OH}$ = –0.4 mA | 2.4 | 3.4 | | 2.4 | 3.4 | | V |
| $V_{OL}$ | $V_{CC}$ = MIN, | $V_{IH}$ = 2 V, | $I_{OL}$ = 16 mA | | 0.2 | 0.4 | | 0.2 | 0.4 | V |
| $I_I$ | $V_{CC}$ = MAX, | $V_I$ = 5.5 V | | | | 1 | | | 1 | mA |
| $I_{IH}$ | $V_{CC}$ = MAX, | $V_I$ = 2.4 V | | | | 40 | | | 40 | μA |
| $I_{IL}$ | $V_{CC}$ = MAX, | $V_I$ = 0.4 V | | | | –1.6 | | | –1.6 | mA |
| $I_{OS}$¶ | $V_{CC}$ = MAX | | | –20 | | –55 | –18 | | –55 | mA |
| $I_{CCH}$ | $V_{CC}$ = MAX, | $V_I$ = 0 V | | | 4 | 8 | | 4 | 8 | mA |
| $I_{CCL}$ | $V_{CC}$ = MAX, | $V_I$ = 4.5 V | | | 12 | 22 | | 12 | 22 | mA |

‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
§ All typical values are at $V_{CC}$ = 5 V, $T_A$ = 25°C.
¶ Not more than one output should be shorted at a time.

## switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | SN5400 SN7400 | | | UNIT |
|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP | MAX | |
| $t_{PLH}$ | A or B | Y | $R_L$ = 400 Ω, $C_L$ = 15 pF | | 11 | 22 | ns |
| $t_{PHL}$ | | | | | 7 | 15 | |

## recommended operating conditions (see Note 4)

| | | SN54LS00 | | | SN74LS00 | | | UNIT |
|---|---|---|---|---|---|---|---|---|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| $V_{CC}$ | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| $V_{IH}$ | High-level input voltage | 2 | | | 2 | | | V |
| $V_{IL}$ | Low-level input voltage | | | 0.7 | | | 0.8 | V |
| $I_{OH}$ | High-level output current | | | –0.4 | | | –0.4 | mA |
| $I_{OL}$ | Low-level output current | | | 4 | | | 8 | mA |
| $T_A$ | Operating free-air temperature | –55 | | 125 | 0 | | 70 | °C |

NOTE 4: All unused inputs of the device must be held at $V_{CC}$ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS† | | | SN54LS00 | | | SN74LS00 | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP‡ | MAX | MIN | TYP‡ | MAX | |
| $V_{IK}$ | $V_{CC}$ = MIN, | $I_I$ = –18 mA | | | | –1.5 | | | –1.5 | V |
| $V_{OH}$ | $V_{CC}$ = MIN, | $V_{IL}$ = MAX, | $I_{OH}$ = –0.4 mA | 2.5 | 3.4 | | 2.7 | 3.4 | | V |
| $V_{OL}$ | $V_{CC}$ = MIN, | $V_{IH}$ = 2 V | $I_{OL}$ = 4 mA | | 0.25 | 0.4 | | 0.25 | 0.4 | V |
| | | | $I_{OL}$ = 8mA | | | | | 0.35 | 0.5 | |
| $I_I$ | $V_{CC}$ = MAX, | $V_I$ = 7 V | | | | 0.1 | | | 0.1 | mA |
| $I_{IH}$ | $V_{CC}$ = MAX, | $V_I$ = 2.7V | | | | 20 | | | 20 | µA |
| $I_{IL}$ | $V_{CC}$ = MAX, | $V_I$ = 0.4 V | | | | –0.4 | | | –0.4 | mA |
| $I_{OS}$§ | $V_{CC}$ = MAX | | | –20 | | –100 | –20 | | –100 | mA |
| $I_{CCH}$ | $V_{CC}$ = MAX, | $V_I$ = 0 V | | | 0.8 | 1.6 | | 0.8 | 1.6 | mA |
| $I_{CCL}$ | $V_{CC}$ = MAX, | $V_I$ = 4.5 V | | | 2.4 | 4.4 | | 2.4 | 4.4 | mA |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at $V_{CC}$ = 5 V, $T_A$ = 25°C.
§ Not more than one output should be shorted at a time.

## switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | SN54LS00 SN74LS00 | | | UNIT |
|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP | MAX | |
| $t_{PLH}$ | A or B | Y | $R_L$ = 2 kΩ, $C_L$ = 15 pF | | 9 | 15 | ns |
| $t_{PHL}$ | | | | | 10 | 15 | |

## recommended operating conditions (see Note 5)

| | | SN54S00 | | | SN74S00 | | | UNIT |
|---|---|---|---|---|---|---|---|---|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| $V_{CC}$ | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| $V_{IH}$ | High-level input voltage | 2 | | | 2 | | | V |
| $V_{IL}$ | Low-level input voltage | | | 0.8 | | | 0.8 | V |
| $I_{OH}$ | High-level output current | | | –1 | | | –1 | mA |
| $I_{OL}$ | Low-level output current | | | 20 | | | 20 | mA |
| $T_A$ | Operating free-air temperature | –55 | | 125 | 0 | | 70 | °C |

NOTE 5: All unused inputs of the device must be held at $V_{CC}$ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

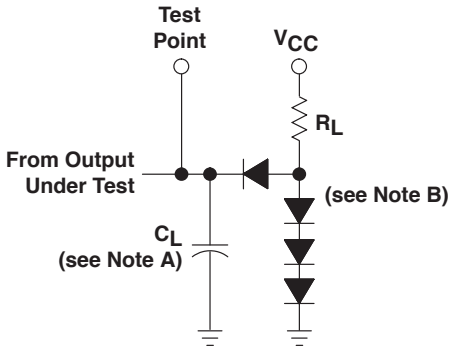
| PARAMETER | TEST CONDITIONS† | | | SN54S00 | | | SN74S00 | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP‡ | MAX | MIN | TYP‡ | MAX | |
| $V_{IK}$ | $V_{CC}$ = MIN, | $I_I$ = –18 mA | | | | –1.2 | | | –1.2 | V |
| $V_{OH}$ | $V_{CC}$ = MIN, | $V_{IL}$ = 0.8 V, | $I_{OH}$ = –1 mA | 2.5 | 3.4 | | 2.7 | 3.4 | | V |
| $V_{OL}$ | $V_{CC}$ = MIN, | $V_{IH}$ = 2 V, | $I_{OL}$ = 20 mA | | | 0.5 | | | 0.5 | V |
| $I_I$ | $V_{CC}$ = MAX, | $V_I$ = 5.5 V | | | | 1 | | | 1 | mA |
| $I_{IH}$ | $V_{CC}$ = MAX, | $V_I$ = 2.7 V | | | | 50 | | | 50 | µA |
| $I_{IL}$ | $V_{CC}$ = MAX, | $V_I$ = 0.5V | | | | –2 | | | –2 | mA |
| $I_{OS}$§ | $V_{CC}$ = MAX | | | –40 | | –100 | –40 | | –100 | mA |
| $I_{CCH}$ | $V_{CC}$ = MAX, | $V_I$ = 0 V | | | 10 | 16 | | 10 | 16 | mA |
| $I_{CCL}$ | $V_{CC}$ = MAX, | $V_I$ = 4.5 V | | | 20 | 36 | | 20 | 36 | mA |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at $V_{CC}$ = 5 V, $T_A$ = 25°C.
§ Not more than one output should be shorted at a time.

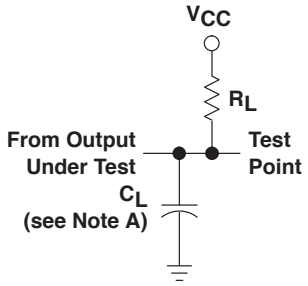
## switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | SN54S00 SN74S00 | | | UNIT |
|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP | MAX | |
| $t_{PLH}$ | A or B | Y | $R_L$ = 280 Ω, $C_L$ = 15 pF | | 3 | 4.5 | ns |
| $t_{PHL}$ | | | | | 3 | 5 | |
| $t_{PLH}$ | A or B | Y | $R_L$ = 280 Ω, $C_L$ = 50 pF | | 4.5 | | ns |
| $t_{PHL}$ | | | | | 5 | | |

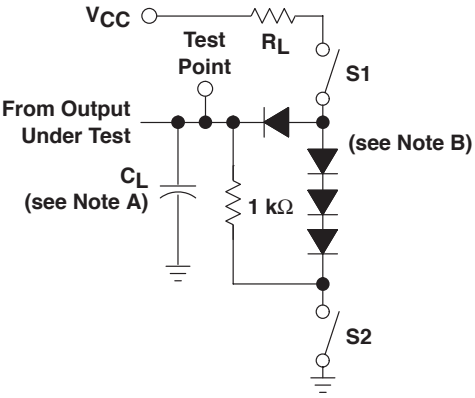
## PARAMETER MEASUREMENT INFORMATION
## SERIES 54/74 DEVICES



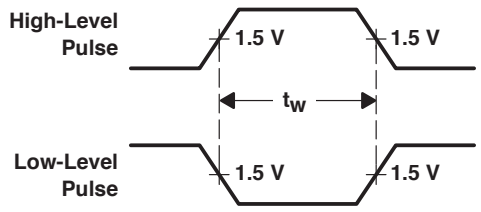

LOAD CIRCUIT
FOR 2-STATE TOTEM-POLE OUTPUTS



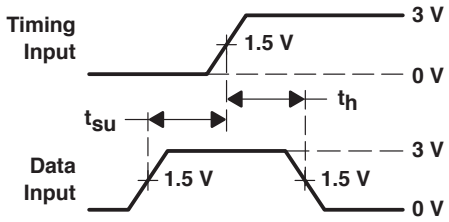

LOAD CIRCUIT
FOR OPEN-COLLECTOR OUTPUTS



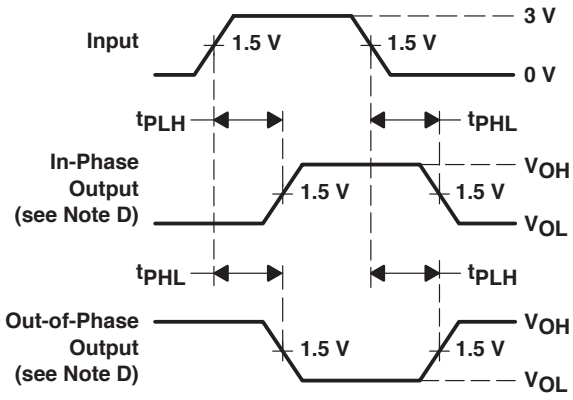

LOAD CIRCUIT
FOR 3-STATE OUTPUTS



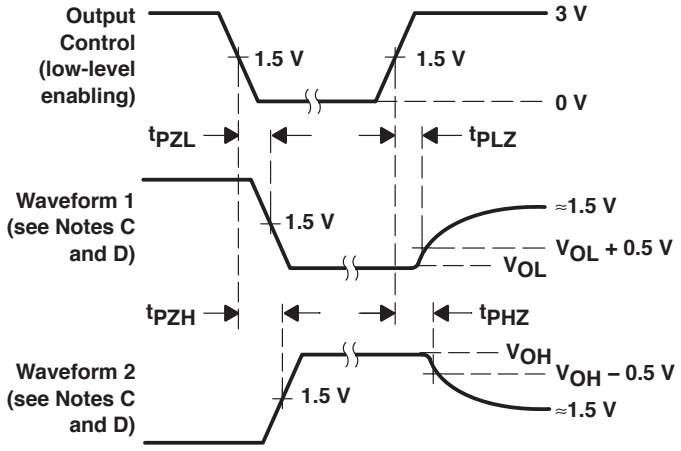

VOLTAGE WAVEFORMS
PULSE DURATIONS




VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES




VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES




VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. $C_L$ includes probe and jig capacitance.
B. All diodes are 1N3064 or equivalent.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. S1 and S2 are closed for $t_{PLH}$, $t_{PHL}$, $t_{PHZ}$, and $t_{PLZ}$; S1 is open and S2 is closed for $t_{PZH}$; S1 is closed and S2 is open for $t_{PZL}$.
E. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O \approx 50\ \Omega$; $t_r$ and $t_f \le 7$ ns for Series 54/74 devices and $t_r$ and $t_f \le 2.5$ ns for Series 54S/74S devices.
F. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuits and Voltage Waveforms**

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| JM38510/00104BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 00104BCA | Samples |
| JM38510/00104BDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 00104BDA | Samples |
| JM38510/07001BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 07001BCA | Samples |
| JM38510/07001BDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 07001BDA | Samples |
| JM38510/30001B2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | JM38510/ 30001B2A | Samples |
| JM38510/30001BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 30001BCA | Samples |
| JM38510/30001BDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 30001BDA | Samples |
| JM38510/30001SCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/30001S CA | Samples |
| JM38510/30001SDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/30001S DA | Samples |
| M38510/00104BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 00104BCA | Samples |
| M38510/00104BDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 00104BDA | Samples |
| M38510/07001BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 07001BCA | Samples |
| M38510/07001BDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 07001BDA | Samples |
| M38510/30001B2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | JM38510/ 30001B2A | Samples |
| M38510/30001BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 30001BCA | Samples |
| M38510/30001BDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 30001BDA | Samples |
| M38510/30001SCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/30001S CA | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| M38510/30001SDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/30001S DA | Samples |
| SN5400J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SN5400J | Samples |
| SN54LS00J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SN54LS00J | Samples |
| SN54S00J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SN54S00J | Samples |
| SN7400D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 7400 | Samples |
| SN7400DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 7400 | Samples |
| SN7400DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 7400 | Samples |
| SN7400N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN7400N | Samples |
| SN7400N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI | 0 to 70 | | |
| SN7400NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN7400N | Samples |
| SN74LS00D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74LS00DBLE | OBSOLETE | SSOP | DB | 14 | | TBD | Call TI | Call TI | 0 to 70 | | |
| SN74LS00DBR | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74LS00DBRE4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74LS00DBRG4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74LS00DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74LS00DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74LS00DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74LS00DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74LS00DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74LS00J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI | 0 to 70 | | |
| SN74LS00N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS00N | Samples |
| SN74LS00NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS00N | Samples |
| SN74LS00NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74LS00 | Samples |
| SN74LS00NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74LS00 | Samples |
| SN74LS00PSR | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74LS00PSRE4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74LS00PSRG4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS00 | Samples |
| SN74S00D | NRND | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | S00 | |
| SN74S00DE4 | NRND | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | S00 | |
| SN74S00DG4 | NRND | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | S00 | |
| SN74S00N | NRND | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN74S00N | |
| SN74S00N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI | 0 to 70 | | |
| SN74S00NE4 | NRND | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN74S00N | |
| SNJ5400J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SNJ5400J | Samples |
| SNJ5400W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SNJ5400W | Samples |
| SNJ5400WA | OBSOLETE | CFP | WA | 14 | | TBD | A42 | N / A for Pkg Type | -55 to 125 | SNJ5400WA | |
| SNJ54LS00FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | SNJ54LS00FK | Samples |
| SNJ54LS00J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SNJ54LS00J | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| SNJ54LS00W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SNJ54LS00W | Samples |
| SNJ54S00FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | SNJ54S 00FK | Samples |
| SNJ54S00J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SNJ54S00J | Samples |
| SNJ54S00W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SNJ54S00W | Samples |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
**TBD:** The Pb-Free/Green conversion plan has not been defined.
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN5400, SN54LS00, SN54LS00-SP, SN54S00, SN7400, SN74LS00, SN74S00 :**

, Catalog: SN7400, SN74LS00, SN54LS00, SN74S00

, Military: SN5400, SN54LS00, SN54S00

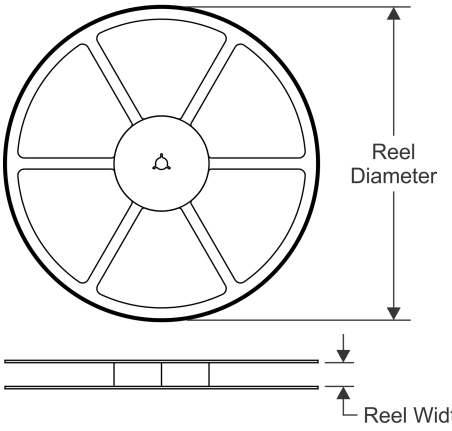
, Space: SN54LS00-SP

NOTE: Qualified Version Definitions:

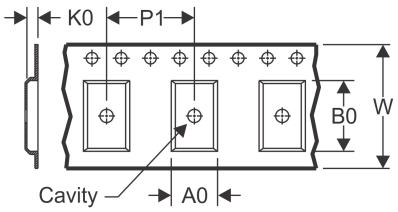
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

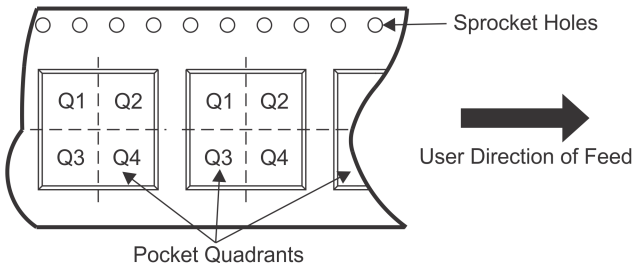



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

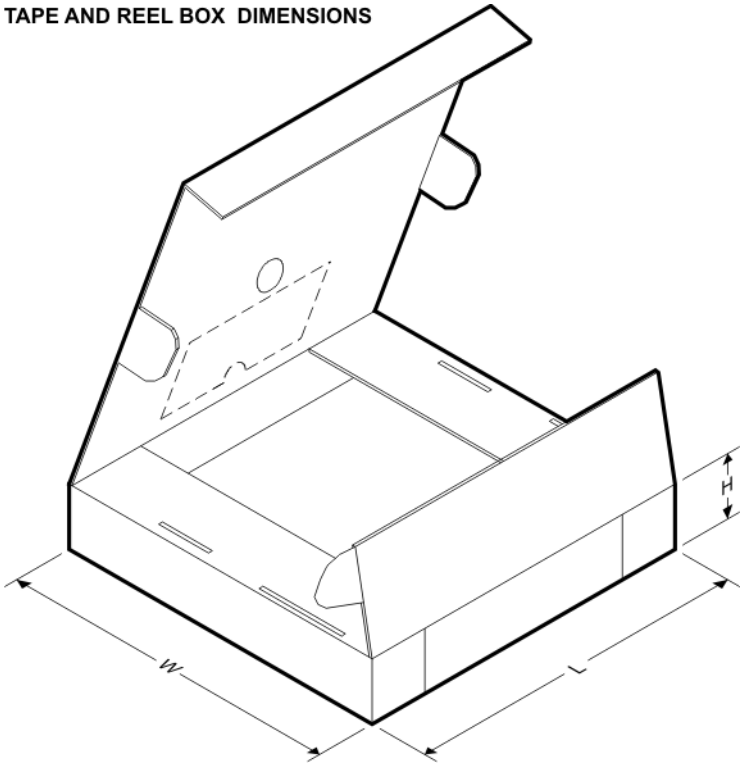
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74LS00DBR | SSOP | DB | 14 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LS00DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LS00NSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LS00PSR | SO | PS | 8 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



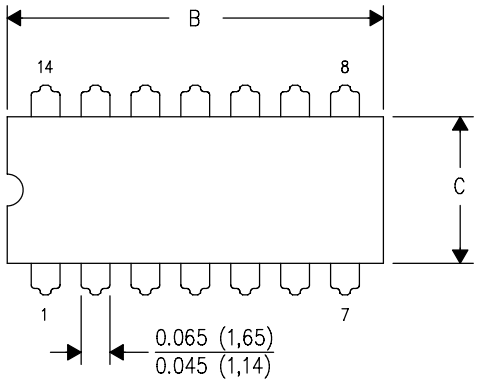

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| SN74LS00DBR | SSOP | DB | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74LS00DR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN74LS00NSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74LS00PSR | SO | PS | 8 | 2000 | 367.0 | 367.0 | 38.0 |

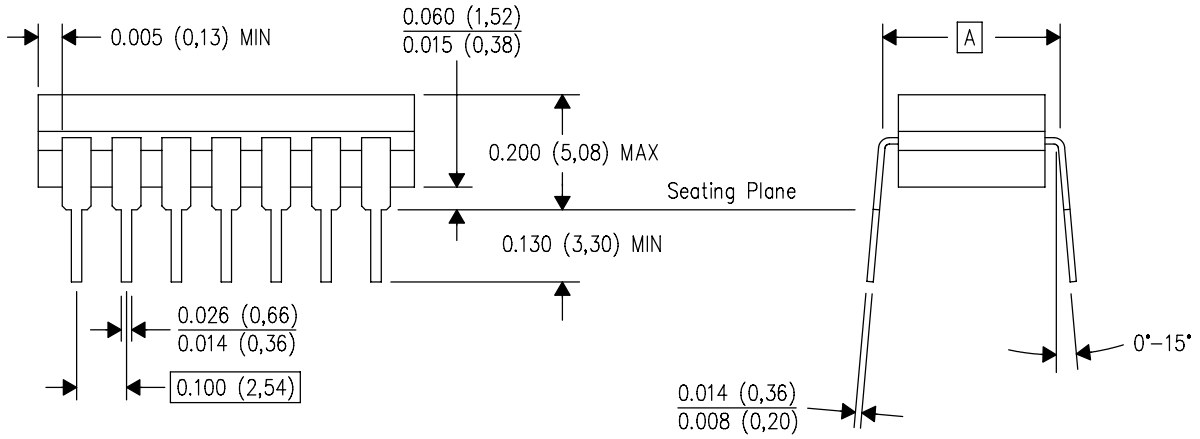
J (R–GDIP–T**)

14 LEADS SHOWN

# CERAMIC DUAL IN–LINE PACKAGE



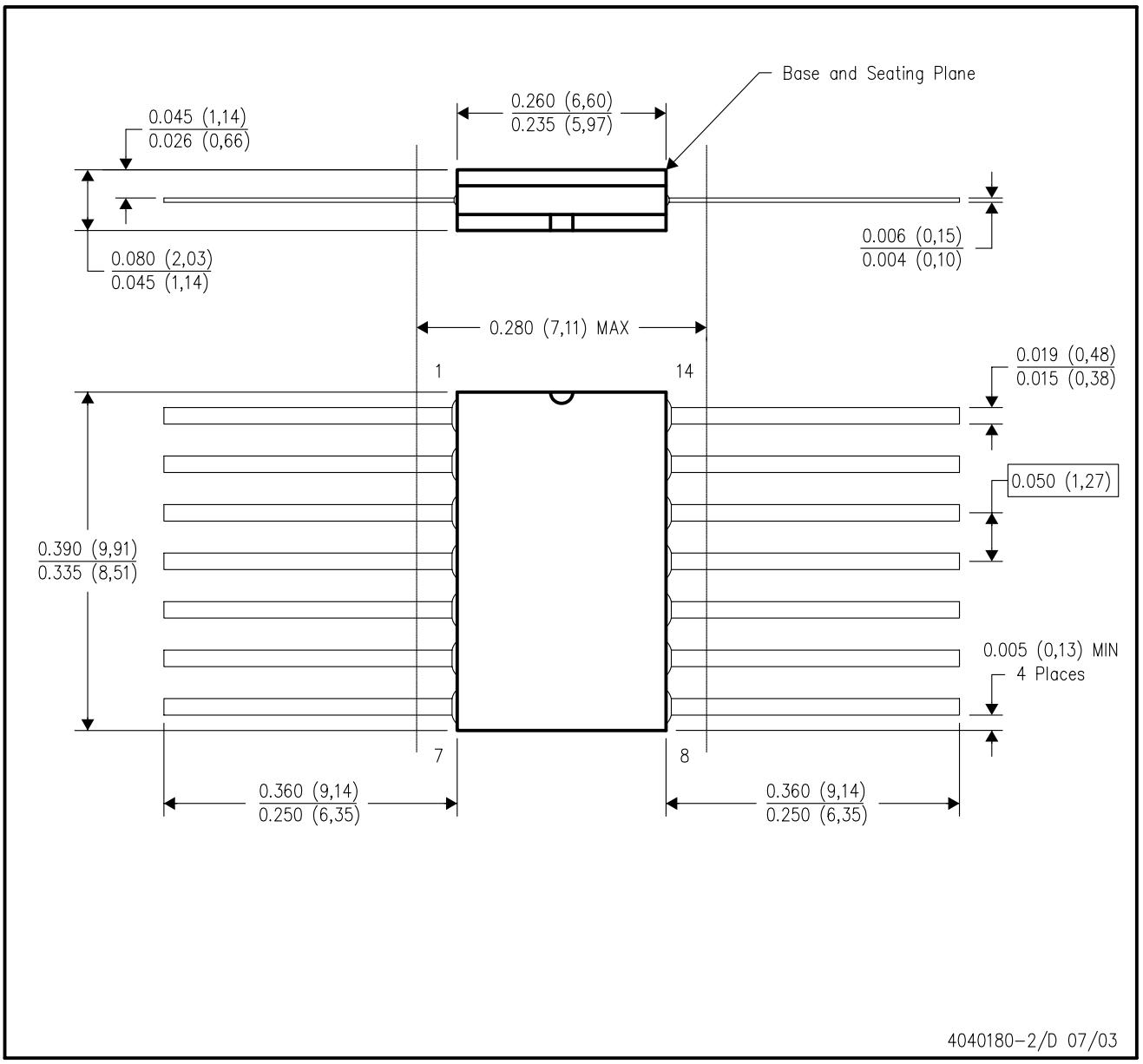

| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---|---|---|---|---|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |




4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

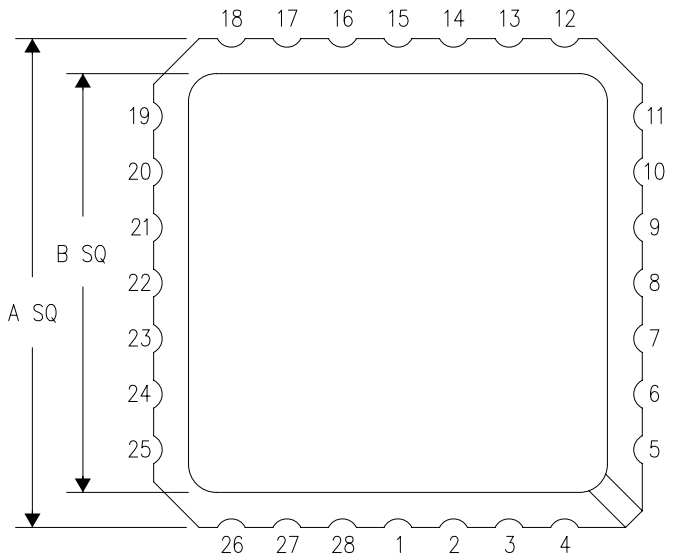
## W (R–GDFP–F14) CERAMIC DUAL FLATPACK



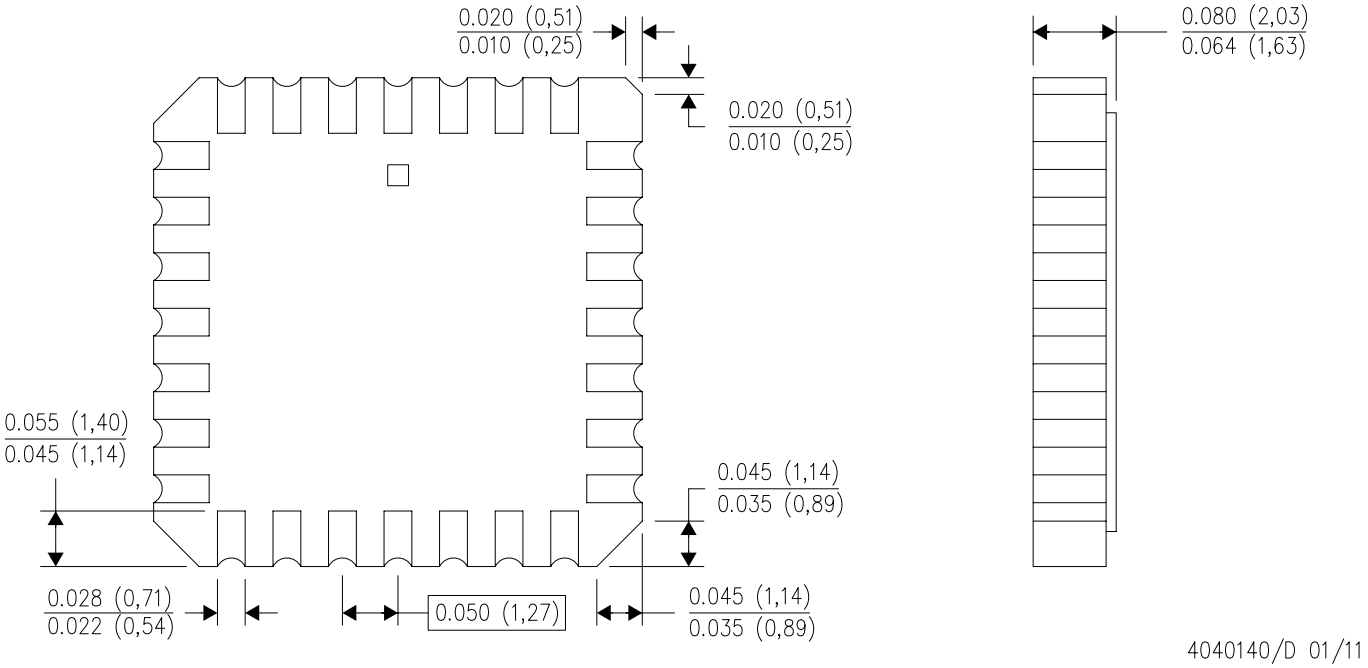

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

# FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN




| NO. OF TERMINALS ** | A | | B | |
|---|---|---|---|---|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |



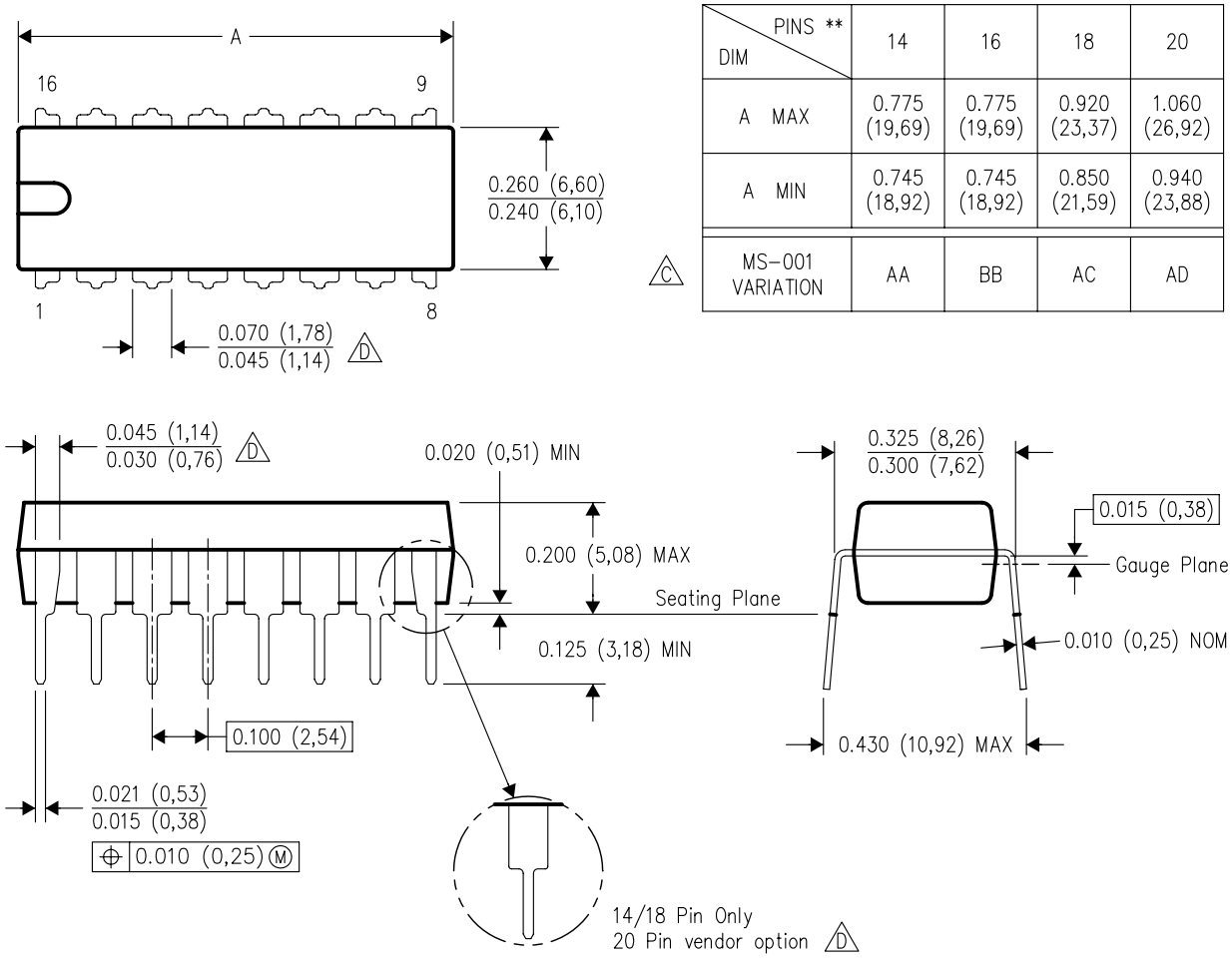

4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

## N (R–PDIP–T**)

## PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

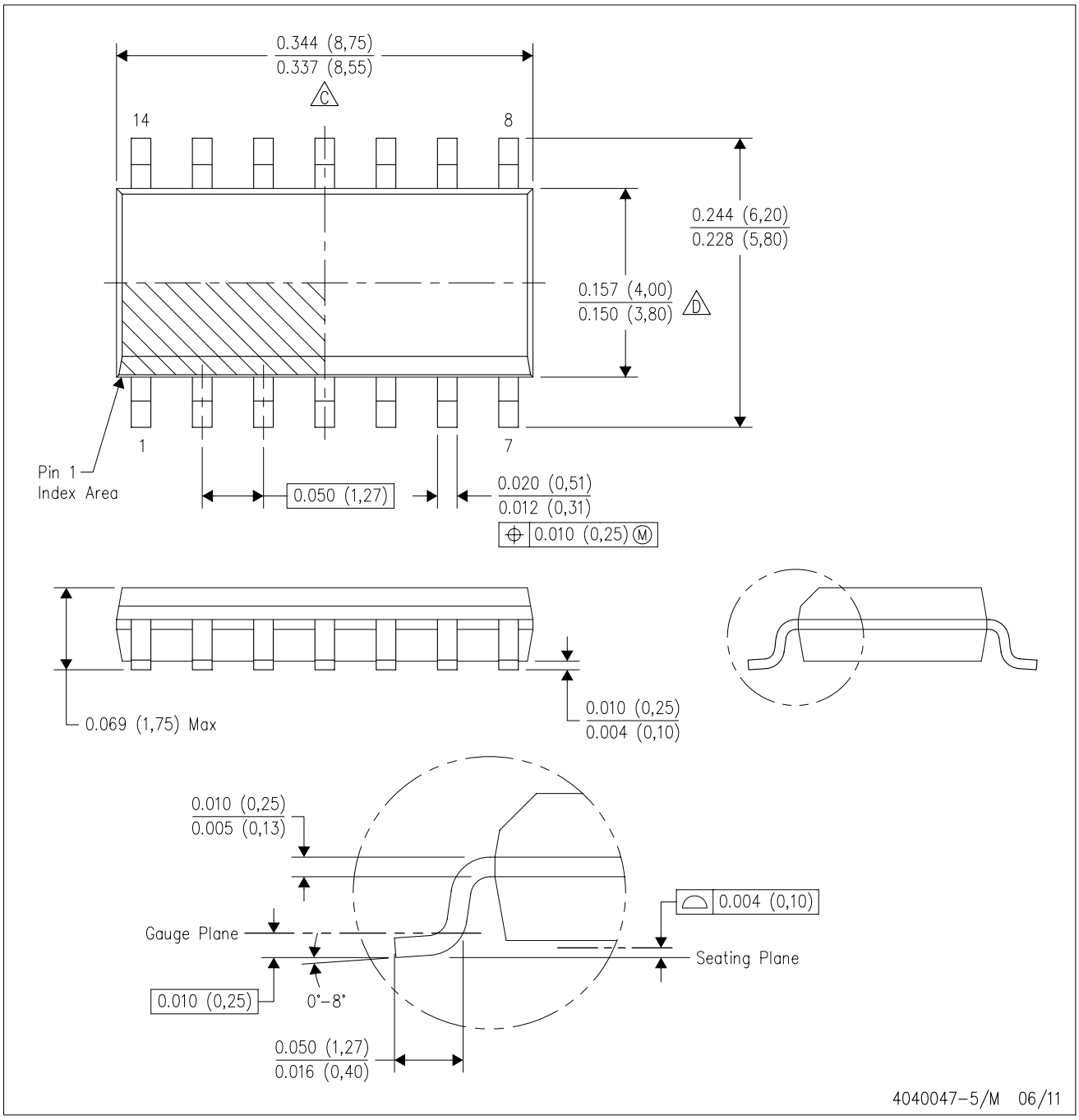



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---|---|---|---|---|
| A MAX | 0.775 (19,69) | 0.775 (19,69) | 0.920 (23,37) | 1.060 (26,92) |
| A MIN | 0.745 (18,92) | 0.745 (18,92) | 0.850 (21,59) | 0.940 (23,88) |
| C MS–001 VARIATION | AA | BB | AC | AD |

4040049/E 12/2002

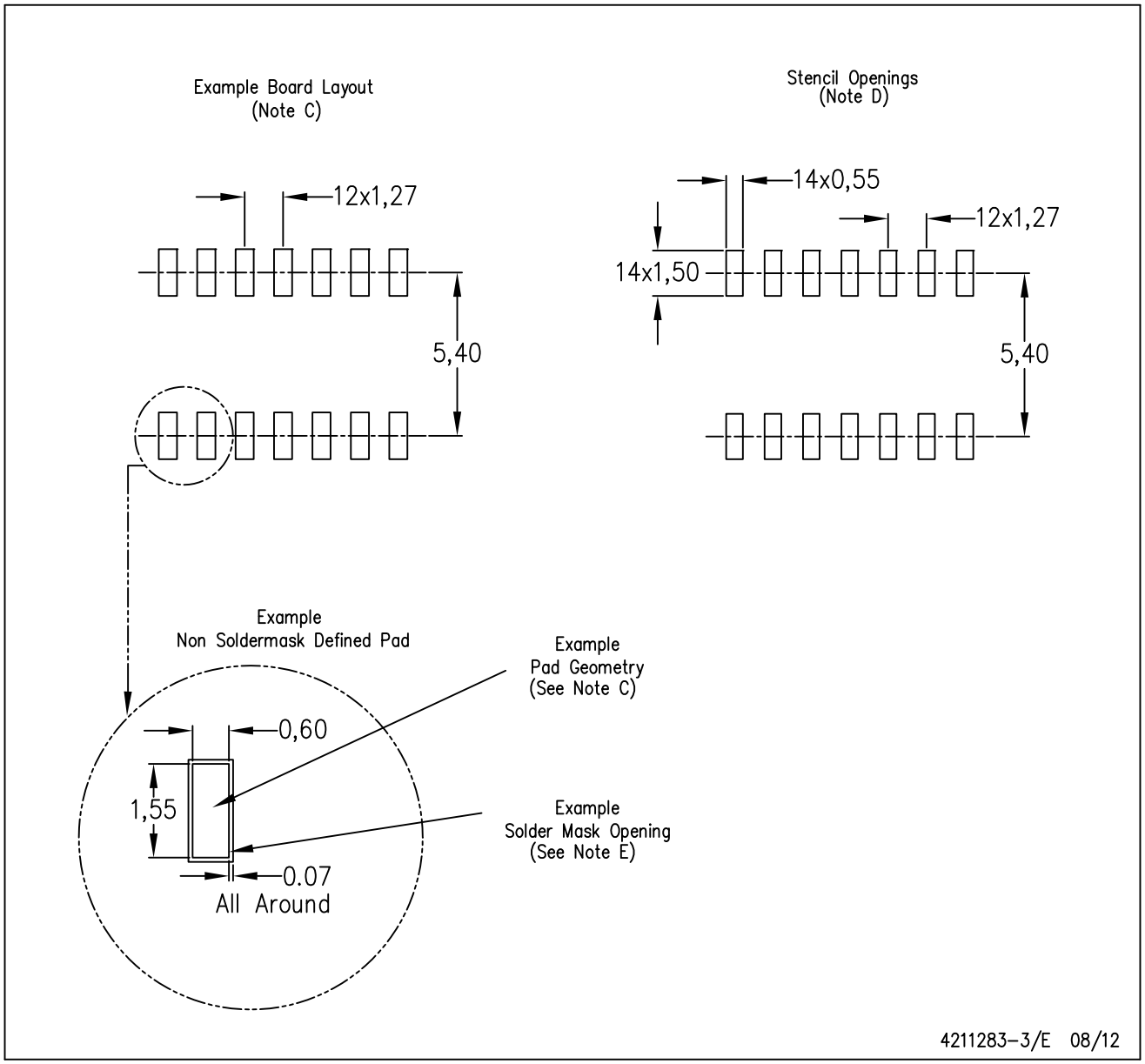
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE




NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

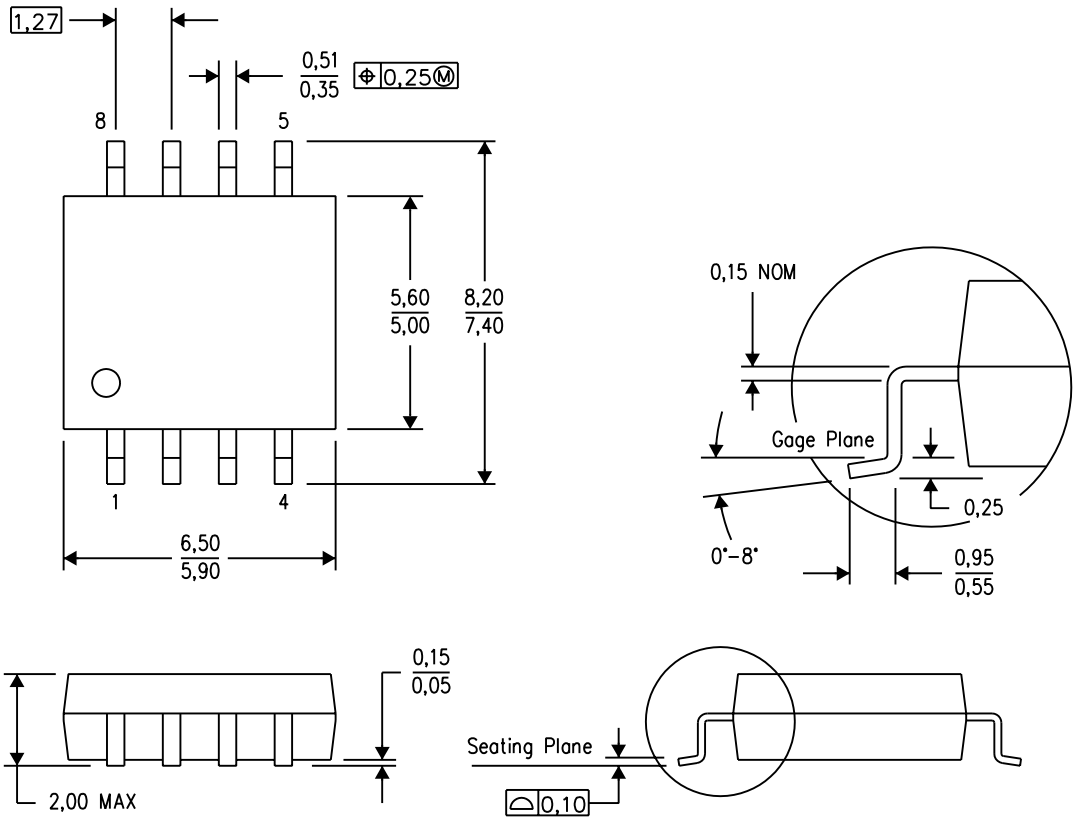
D (R–PDSO–G14) PLASTIC SMALL OUTLINE




NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

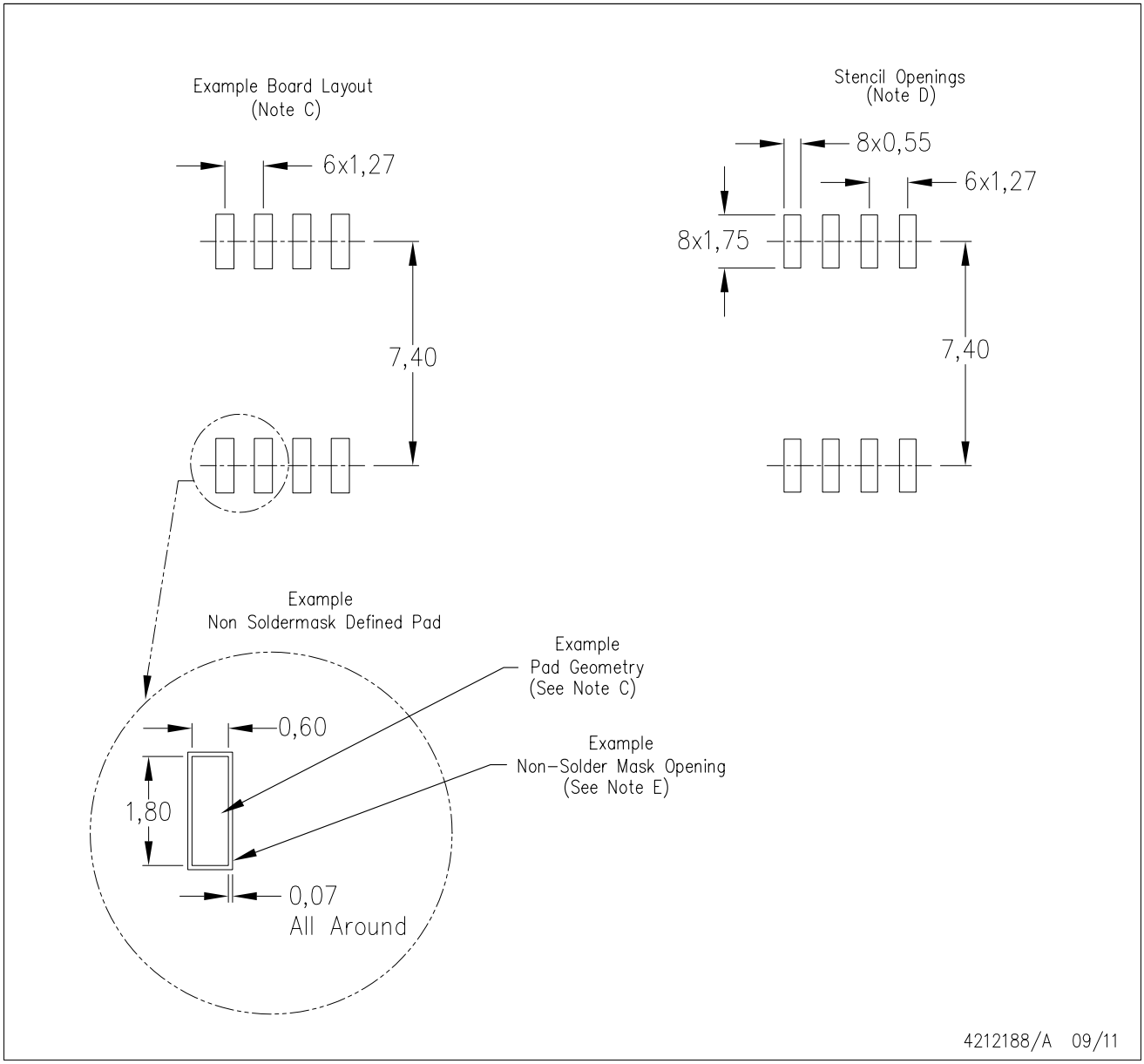
## MECHANICAL DATA

**PS (R-PDSO-G8)** **PLASTIC SMALL-OUTLINE PACKAGE**




NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R–PDSO–G8) PLASTIC SMALL OUTLINE

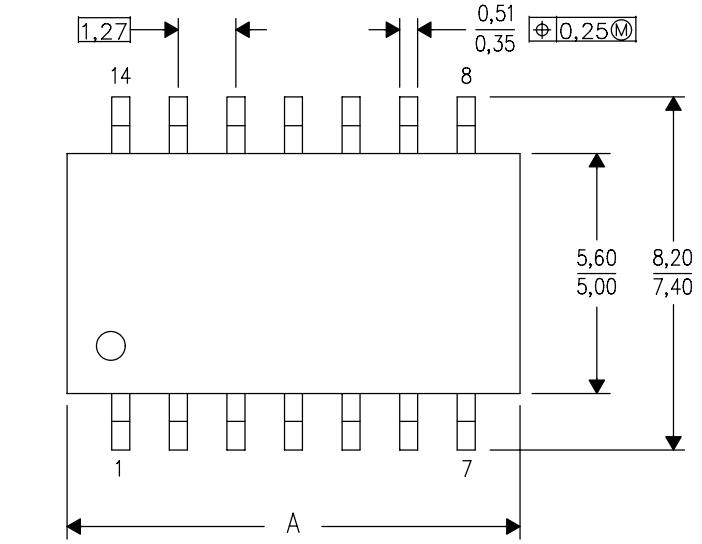


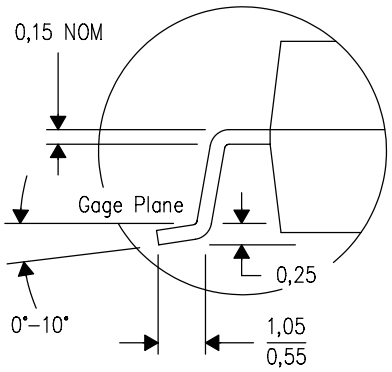

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

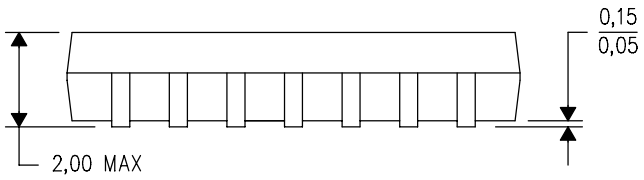
## MECHANICAL DATA

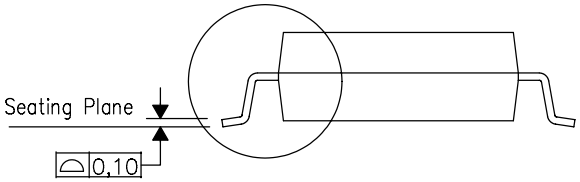
**NS (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**




| DIM \ PINS ** | 14 | 16 | 20 | 24 |
|---|---|---|---|---|
| A MAX | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN | 9,90 | 9,90 | 12,30 | 14,70 |

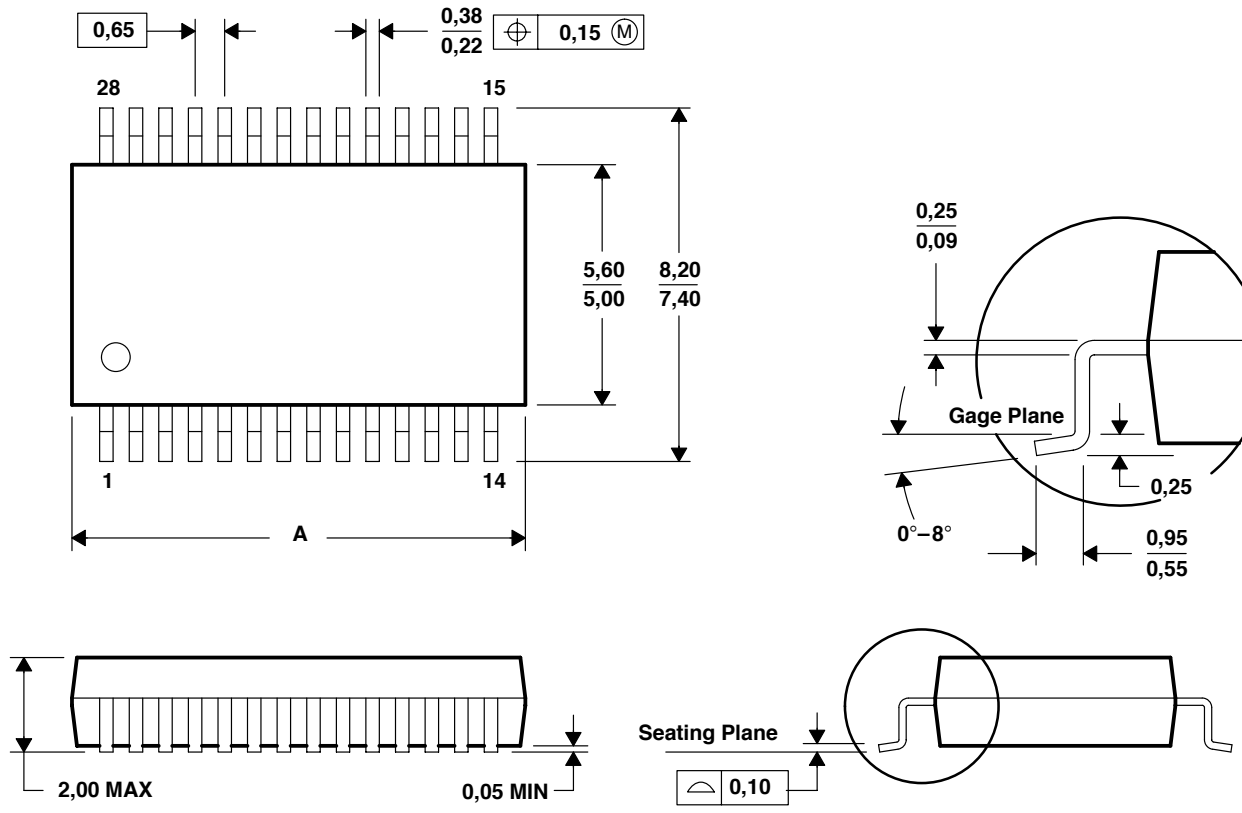
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## DB (R-PDSO-G**)

## PLASTIC SMALL-OUTLINE

**28 PINS SHOWN**




| DIM \ PINS ** | 14 | 16 | 20 | 24 | 28 | 30 | 38 |
|---|---|---|---|---|---|---|---|
| A MAX | 6,50 | 6,50 | 7,50 | 8,50 | 10,50 | 10,50 | 12,90 |
| A MIN | 5,90 | 5,90 | 6,90 | 7,90 | 9,90 | 9,90 | 12,30 |

**4040065 /E 12/01**

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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